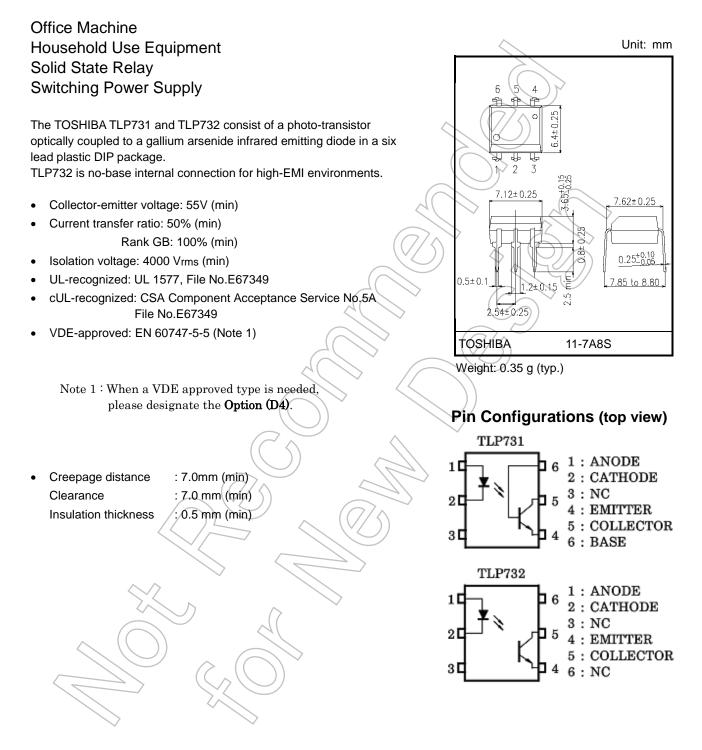
TOSHIBA Photocoupler IRED & Photo-Transistor

TLP731, TLP732



TOSHIBA

Current Transfer Ratio

Classification	I = 3 IIA, VCE		Marking Of Classification
(Note 1)	Min	Max	
Blank	50	600	Blank, Y•, YE, G, G•, GR, B, BL, GB
Rank Y	50	150	YE, Y
Rank GR	100	300	GR, G, G•
Rank BL	200	600	BL, B
Rank GB	100	600	GB, GR, G, G [•] , BL, B,

Note: The product with the Rank Y and BL are limited in production. For details, please contact your nearest Toshiba sales representative

Note 1: Ex. rank GB: TLP731 (GB)

Note: Application type name for certification test,

please use standard product type name, i.e. TLP731(GB): TLP731 TLP732(GB): TLP732

Absolute Maximum Ratings (Ta = 25°C)

$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$		Characteristic	Symbol	Rating	Unit	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $			Oymbol	rtating	Onit	
$ \begin{array}{ c c c c } \hline Peak forward current (100 \mu s pulse, 100 pps) & IFP & 1 & A \\ \hline Power dissipation & PD & 70 & mW \\ \hline Power dissipation derating (Ta \geq 39°C) & \Delta PD / °C & -0.82 & mW / °C \\ \hline Reverse voltage & VR & 5 & V \\ \hline Junction temperature & T_j & 125 & °C \\ \hline Collector-emitter voltage & VCEO & 55 & V \\ \hline Collector-base voltage (TLP731) & VCBO & 80 & V \\ \hline Emitter-collector voltage & VECO & 7 & V \\ \hline Emitter-collector voltage & VECO & 7 & V \\ \hline Collector current & Ic & 50 & mA \\ \hline Power dissipation derating (Ta \geq 25°C) & \Delta Pc / °C & -1.5 & mW / °C \\ \hline Junction temperature & T_j & 125 & °C \\ \hline Storage temperature range & T_{stg} & -55 to 125 & °C \\ \hline Operating temperature range & T_{stg} & 260 & °C \\ \hline Lead soldering temperature (10 s) & T_{sol} & 260 & °C \\ \hline \end{array}$		Forward current	lF	60	mA	
Power dissipationPD70mWPower dissipation derating (Ta \geq 39°C) Δ PD/°C-0.82mW / °CReverse voltageVR5VJunction temperatureTj125°CCollector-emitter voltageVCEO55VCollector-base voltage (TLP731)VCBO80VEmitter-collector voltageVECO7VEmitter-base voltage (TLP731)VEBO7VCollector currentIc50mAPower dissipationPc150mWPower dissipation derating (Ta \geq 25°C) Δ Pc / °C-1.5mW / °CJunction temperatureTi125°CStorage temperature rangeTsig-55 to 125°COperating temperature rangeTopr-55 to 100°CLead soldering temperature (10 s)Tsol260°C		Forward current derating (Ta ≥ 39°C)	ΔI _F / °C	-0.7	mA / °C	
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$		Peak forward current (100µs pulse, 100pps)	IFP	1	A	
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	LED	Power dissipation	PD	70	mW	
$\frac{1}{1} \frac{1}{1} \frac{1}$		Power dissipation derating (Ta ≥ 39°C)	ΔP _D /°C	-0.82	mW / °C	\mathcal{A}
$\frac{1}{10} = \frac{1}{10} $		Reverse voltage		5	(A)	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		Junction temperature	Tj	125	(°¢)
$\frac{1}{2} \underbrace{ \begin{array}{c} \text{belocity basis (if L i O i)} \\ \text{Emitter-collector voltage} \\ \hline \text{Emitter-collector voltage} \\ \hline \text{Emitter-base voltage (TLP731)} \\ \hline \text{Verse} \\ \hline \text{Verse} \\ \hline \text{Collector current} \\ \hline \text{Collector current} \\ \hline \text{Power dissipation} \\ \hline \text{Power dissipation derating (Ta \ge 25^{\circ}\text{C})} \\ \hline \text{Junction temperature} \\ \hline \text{Tj} \\ \hline \text{125} \\ \hline \text{CC} \\ \hline \text{Storage temperature range} \\ \hline \text{Tstg} \\ \hline \text{-55 to 125} \\ \hline \text{CC} \\ \hline \text{Operating temperature (10 s)} \\ \hline \text{Tsol} \\ \hline \text{Z60} \\ \hline \text{CC} \\ \hline \ \ \text{CC} \\ \hline \ \text{CC} \\ \hline \ \ \ \text{CC} \\ \hline \ \ \ \text{CC} \\ \hline \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$		Collector-emitter voltage		55) v	
$\frac{1}{2} \frac{1}{2} \frac{1}$		Collector-base voltage (TLP731)	Vсво	80)y	
$\begin{tabular}{ c c c c c } \hline Power dissipation & Pc & 150 & mW \\ \hline Power dissipation derating (Ta $$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$		Emitter-collector voltage	VECO		V	\bigcirc
$\begin{tabular}{ c c c c c } \hline Power dissipation & Pc & 150 & mW \\ \hline Power dissipation derating (Ta $$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$	ctor	B Emitter-base voltage (TLP731)		Z	V	
$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	Dete	o Collector current		50	mA	$\langle S \rangle$
Junction temperature Tj 125 °C Storage temperature range Tstg -55 to 125 °C Operating temperature range Topr -55 to 100 °C Lead soldering temperature (10 s) Tsol 260 °C		Power dissipation	Pc	150	mW	YM
Storage temperature range Tstg -55 to 125 °C Operating temperature range Topr -55 to 100 °C Lead soldering temperature (10 s) Tsol 260 °C		Power dissipation derating (Ta ≥ 25°C)	ΔPc/°C	-1.5	mW / °C	
Operating temperature range Topr -55 to 100 °C Lead soldering temperature (10 s) Tsol 260 °C		Junction temperature	Ĩ	125	°C	
Lead soldering temperature (10 s) T _{sol} 260 °C	Storage temperature range		Tstg	-55 to 125	್ರಿ)
	Operating temperature range		Topr	-55 to 100 🤇	∕~¢	
	Lead soldering temperature (10 s)		Tsol	260	°C	
I Utal package power dissipation	Total package power dissipation		Рт	250	mW	
Total package power dissipation derating (Ta $\ge 25^{\circ}$ C) $\Delta P_T / ^{\circ}$ C -2.5 mW / $^{\circ}$ C	Total package power dissipation derating $(Ta \ge 25^{\circ}C)$		ΔP _T / °C	-2.5	/ mW / °C	
Isolation voltage (AC, 60 s, R.H. ≤ 60 %) (Note 1) BVs 4000 Vrms	Isolatio	on voltage (AC, 60 s, R.H. ≤ 60 %) (Note 1)	BVs	4000	Vrms	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Device considered a two terminal device: LED side pins shorted together and detector side pins shorted together.

Recommended Operating Conditions

Characteristic	Symbol	Min	Тур.	Max	Unit
Supply voltage	Vcc	—	5	24	V
Forward current	lF	—	16	25	mA
Collector current	lc	—	1	10	mA
Operating temperature	Topr	-25		85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit	
	Forward voltage		VF	I _F = 10 mA	1.0	1.15	1.3	V
LED	Reverse current		I _R	V _R = 5 V	_	—	10	μA
	Capacitance		CT	V = 0 V, f = 1 MHz	/	30	_	pF
	Collector-emitter breakdown voltage		V _{(BR)CEO}	I _C = 0.5 mA	55		Ι	V
	Emitter-collector breakdown voltage		V _{(BR)ECO}	I _E = 0.1mA		_	Ι	V
	Collector-base breakdown voltage (TL	LP731)	V(BR)CBO	IC = 0.1mA	80	_	_	V
<u> </u>	Emitter-base breakdown voltage (TL	LP731)	V(BR)EBO	IE = 0.1mA	7	- (_	V
Detector	Collector dark current		1050	Vce = 24 V	_	10	100	nA
Det			ICEO	Vce = 24 V, Ta = 85 °C	- 0	2	50	μA
	Collector dark current (TL	LP731)	ICER	Vce = 24 V, Ta = 85 °C Rbe = 1 MΩ	Š	0.5	10	μA
	Collector dark current (TL	LP731)	ICBO	V _{CB} = 10 V		0.1	_	nA
	DC forward current gain (TL	LP731)	hFE	VCE = 5 V, IC = 0.5 mA	Ð	400	_	_
	Capacitance collector to emitter		CCE	V = 0 V, f = 1 MHz		10	—	pF

Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	ň	Min	Тур.	Max	Unit
Current transfer ratio		I _F = 5 mA, V _{CE} = 5 V		50	_	600	%
			Rank GB	100	_	600	/0
Saturated CTR		I _F = 1 mA, V _{CE} = 0.4 V		_	60	_	%
Saturated CTR	IC / IF (sat)	$(\overline{\Omega})$	Rank GB	30	_	—	70
Base photo-current (TLP731)	Ірв	$I_F = 5 \text{ mA}, V_{CB} = 5 \text{ V}$		_	10	_	μA
		Ic = 2.4 mA, I _F = 8 mA		—	_	0.4	
Collector-emitter saturation voltage	VCE (sat)	I _C = 0.2 mA, I _F = 1 mA		—	0.2	-	V
		\geq	Rank GB	_		0.4	

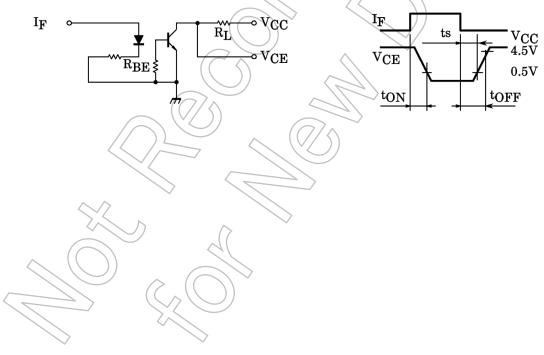
Isolation Characteristics (Ta = 25°C)

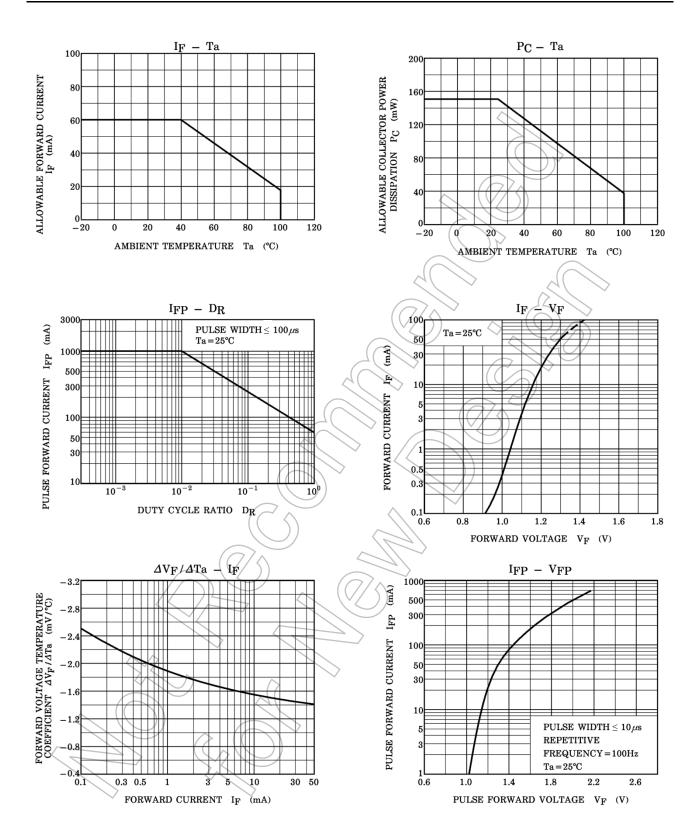
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Capacitance (input to output)	CS	V _S = 0 V, f = 1 MHz	—	0.8	_	pF
Isolation resistance	Rs	V _S = 500 V, R.H.≤60 %	1×10 ¹²	10 ¹⁴	_	Ω
Isolation voltage	BVs	AC, 60 s	4000		_	Vrms

Switching Characteristics (Ta = 25°C)

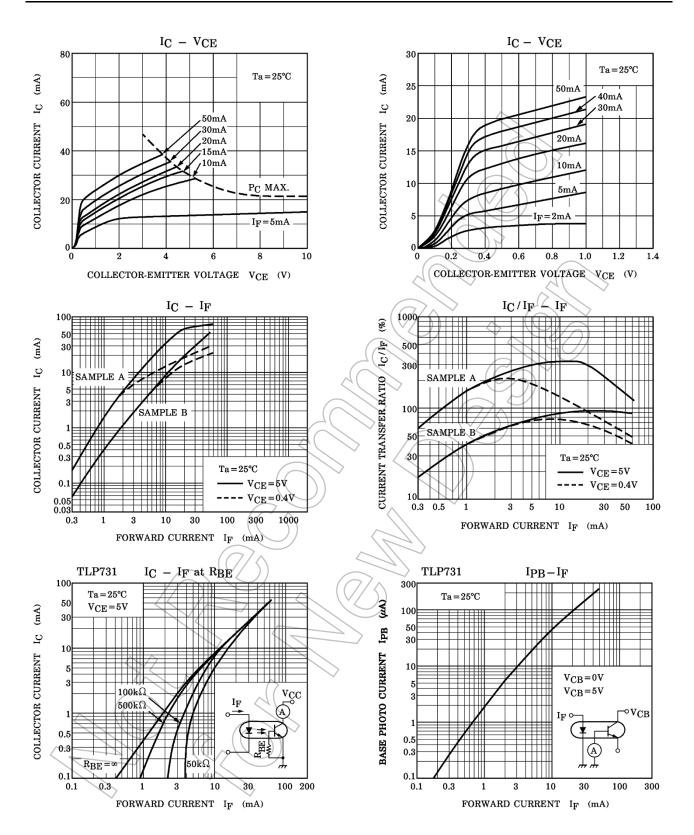
Characteristic	Symbol	Test Condition Min Typ. Max Unit
Rise time	tr	- 2 -
Fall time	tf	$V_{CC} = 10 V, I_C = 2 mA$ — 3 —
Turn-on time	t _{on}	$R_L = 100 \Omega$ μ s μ s
Turn-off time	t _{off}	- 3 10
Turn-on time	ton	$R_{L} = 1.9 k\Omega(Fig.1)$ - 2 -
Storage time	ts	$R_{BE} = open$ μs
Turn-off time	tOFF	V _{CC} = 5 V, I _F = 16 mA 25 -
Turn-on time	ton	$R_{L} = 1.9 k\Omega (Fig.1) \qquad \qquad 2 \qquad -$
Storage time	ts	$R_{BE} = 220 k\Omega (TLP731)$ 12 – μs
Turn-off time	tOFF	$V_{CC} = 5 V_{s} I_{F} = 16 \text{ mA}$ - 20 -

Fig. 1 Switching time test circuit

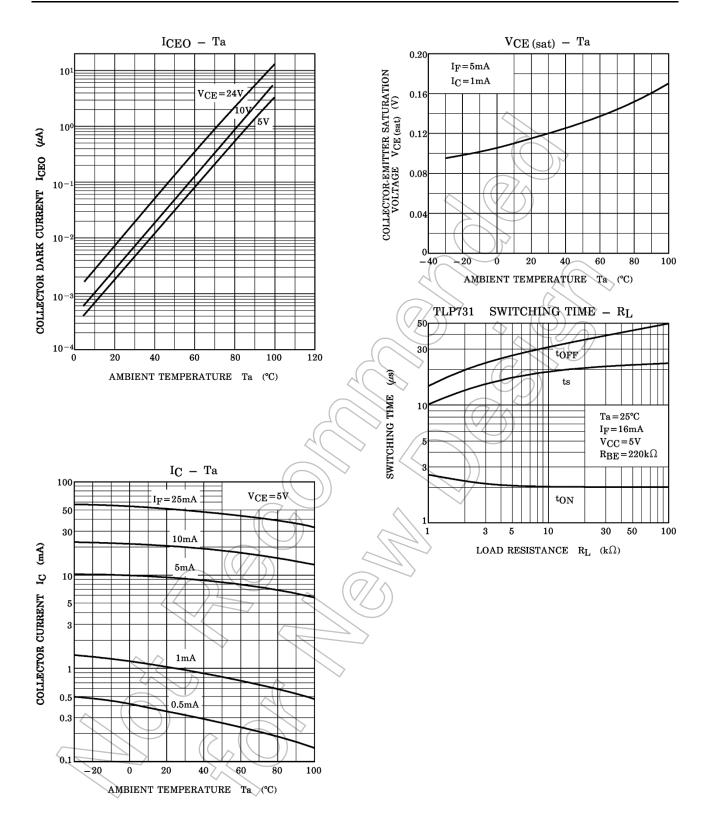




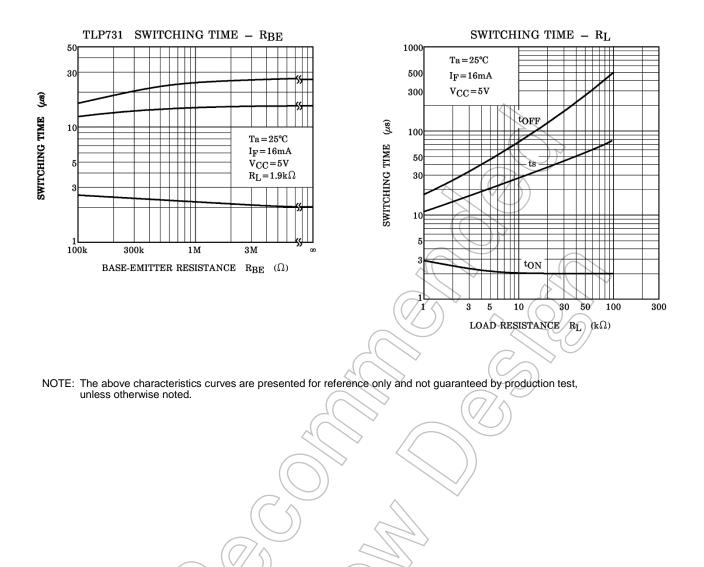
NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



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